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## Hall ICs

# Omnipolar Detection Hall ICs



BU52001GUL, BU52011HFV, BU52021HFV, BU52015GUL, BU52025G,  
 BU52051NVX, BU52053NVX, BU52054GWZ, BU52055GWZ,  
 BU52056NVX, BU52061NVX, BD7411G

No.10045EFT02

## ●Description

The omnipolar Hall ICs are magnetic switches that can operate both S-and N-pole, upon which the output goes from Hi to Low. In addition to regular single-output Hall ICs, We offer a lineup of dual-output units with a reverse output terminal (active High).

## ●Features

- 1) Omnipolar detection
- 2) Micro power operation (small current using intermittent operation method)(BD7411G is excluded.)
- 3) Ultra-compact and thin wafer level CSP4 package (BU52054GWZ, BU52055GWZ)
- 4) Ultra-compact wafer level CSP4 package (BU52015GUL, BU52001GUL)
- 5) Ultra-Small outline package SSON004X1216 (BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX)
- 6) Ultra-Small outline package HVSO5 (BU52011HFV, BU52021HFV)
- 7) Small outline package (BU52025G, BD7411G)
- 8) Line up of supply voltage  
 For 1.8V Power supply voltage (BU52054GWZ, BU52055GWZ, BU52015GUL, BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX, BU52011HFV)  
 For 3.0V Power supply voltage (BU52001GUL)  
 For 3.3V Power supply voltage (BU52021HFV, BU52025G)  
 For 5.0V Power supply voltage (BD7411G)
- 9) Dual output type (BU52015GUL)
- 10) High ESD resistance 8kV (HBM) (6kV for BU52056NVX)

## ●Applications

Mobile phones, notebook computers, digital video camera, digital still camera, white goods etc.

## ●Lineup matrix

Product name	Supply voltage (V)	Operate point (mT)	Hysteresis (mT)	Period (ms)	Supply current (AVG) (A)	Output type	Package
BU52054GWZ	1.65~3.60	+/-6.3 *	0.9	50	5.0μ	CMOS	UCSP35L1
BU52055GWZ	1.65~3.60	+/-4.1 *	0.8	50	5.0μ	CMOS	UCSP35L1
BU52015GUL	1.65~3.30	+/-3.0 *	0.9	50	5.0μ	CMOS	VCSP50L1
BU52001GUL	2.40~3.30	+/-3.7 *	0.8	50	8.0μ	CMOS	VCSP50L1
BU52061NVX	1.65~3.60	+/-3.3 *	0.9	50	4.0μ	CMOS	SSON004X1216
BU52053NVX	1.65~3.60	+/-3.0 *	0.9	50	5.0μ	CMOS	SSON004X1216
BU52051NVX	1.65~3.30	+/-3.0 *	0.9	50	5.0μ	CMOS	SSON004X1216
BU52056NVX	1.65~3.60	+/-4.6 *	0.8	50	5.0μ	CMOS	SSON004X1216
BU52011HFV	1.65~3.30	+/-3.0 *	0.9	50	5.0μ	CMOS	HVSO5
BU52021HFV	2.40~3.60	+/-3.7 *	0.8	50	8.0μ	CMOS	HVSO5
BU52025G	2.40~3.60	+/-3.7 *	0.8	50	8.0μ	CMOS	SSOP5
BD7411G	4.50~5.50	+/-3.4 *	0.4	-	2.0m	CMOS	SSOP5

\*Plus is expressed on the S-pole; minus on the N-pole



● Absolute maximum ratings

BU52054GWZ, BU52055GWZ (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※1</sup>	V
Output Current	I <sub>OUT</sub>	±0.5	mA
Power Dissipation	P <sub>d</sub>	100 <sup>※2</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※1. Not to exceed P<sub>d</sub>

※2. Reduced by 1.00mW for each increase in Ta of 1°C over 25°C (mounted on 24mm × 20mm Glass-epoxy PCB)

BU52015GUL (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※3</sup>	V
Output Current	I <sub>OUT</sub>	±0.5	mA
Power Dissipation	P <sub>d</sub>	420 <sup>※4</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※3. Not to exceed P<sub>d</sub>

※4. Reduced by 4.20mW for each increase in Ta of 1°C over 25°C (mounted on 50mm × 58mm Glass-epoxy PCB)

BU52001GUL (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※5</sup>	V
Output Current	I <sub>OUT</sub>	±1	mA
Power Dissipation	P <sub>d</sub>	420 <sup>※6</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※5. Not to exceed P<sub>d</sub>

※6. Reduced by 4.20mW for each increase in Ta of 1°C over 25°C (mounted on 50mm × 58mm Glass-epoxy PCB)

BU52061NVX, BU52053NVX, BU52051NVX,  
BU52056NVX (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※7</sup>	V
Output Current	I <sub>OUT</sub>	±0.5	mA
Power Dissipation	P <sub>d</sub>	2049 <sup>※8</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※7. Not to exceed P<sub>d</sub>

※8. Reduced by 4.20mW for each increase in Ta of 1°C over 25°C (mounted on 50mm × 58mm Glass-epoxy PCB)

BU52011HFV (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※9</sup>	V
Output Current	I <sub>OUT</sub>	±0.5	mA
Power Dissipation	P <sub>d</sub>	536 <sup>※10</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※9. Not to exceed P<sub>d</sub>

※10. Reduced by 5.36mW for each increase in Ta of 1°C over 25°C (mounted on 70mm × 70 mm × 1.6mm Glass-epoxy PCB)

BU52021HFV (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※11</sup>	V
Output Current	I <sub>OUT</sub>	±1	mA
Power Dissipation	P <sub>d</sub>	536 <sup>※12</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※11. Not to exceed P<sub>d</sub>

※12. Reduced by 5.36mW for each increase in Ta of 1°C over 25°C (mounted on 70mm × 70 mm × 1.6mm Glass-epoxy PCB)

BU52025G (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.1~+4.5 <sup>※13</sup>	V
Output Current	I <sub>OUT</sub>	±1	mA
Power Dissipation	P <sub>d</sub>	540 <sup>※14</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40~+125	°C

※13. Not to exceed P<sub>d</sub>

※14. Reduced by 5.40mW for each increase in Ta of 1°C over 25°C (mounted on 70mm × 70 mm × 1.6mm Glass-epoxy PCB)

BD7411G (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	V <sub>DD</sub>	-0.3~+7.0 <sup>※15</sup>	V
Output Current	I <sub>OUT</sub>	±1	mA
Power Dissipation	P <sub>d</sub>	540 <sup>※16</sup>	mW
Operating Temperature Range	T <sub>opr</sub>	-40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150	°C

※15. Not to exceed P<sub>d</sub>

※16. Reduced by 5.40mW for each increase in Ta of 1°C over 25°C (mounted on 70mm × 70 mm × 1.6mm Glass-epoxy PCB)

●Magnetic, Electrical characteristics

BU52054GWZ (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.60	V	
Operate Point	$B_{opS}$	-	6.3	7.9	mT	
	$B_{opN}$	-7.9	-6.3	-		
Release Point	$B_{rpS}$	3.5	5.4	-	mT	
	$B_{rpN}$	-	-5.4	-3.5		
Hysteresis	$B_{hysS}$	-	0.9	-	mT	
	$B_{hysN}$	-	0.9	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※17
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※17
Supply Current	$I_{DD(AVG)}$	-	5	8	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	2.8	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	1.8	-	$\mu A$	During Standby Time Value

※17 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.  
 After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.  
 Radiation hardness is not designed.

BU52055GWZ (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.60	V	
Operate Point	$B_{opS}$	-	4.1	5.5	mT	
	$B_{opN}$	-5.5	-4.1	-		
Release Point	$B_{rpS}$	1.5	3.3	-	mT	
	$B_{rpN}$	-	-3.3	-1.5		
Hysteresis	$B_{hysS}$	-	0.8	-	mT	
	$B_{hysN}$	-	0.8	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※18
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※18
Supply Current	$I_{DD(AVG)}$	-	5	8	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	2.8	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	1.8	-	$\mu A$	During Standby Time Value

※18 B = Magnetic flux density

1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.

Radiation hardness is not designed.

BU52015GUL (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.30	V	
Operate Point	$B_{opS}$	-	3.0	5.0	mT	
	$B_{opN}$	-5.0	-3.0	-		
Release Point	$B_{rpS}$	0.6	2.1	-	mT	
	$B_{rpN}$	-	-2.1	-0.6		
Hysteresis	$B_{hysS}$	-	0.9	-	mT	
	$B_{hysN}$	-	0.9	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	OUT1: $B_{rpN} < B < B_{rpS}$ ※19 OUT2: $B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = -0.5mA$
Output Low Voltage	$V_{OL}$	-	-	0.2	V	OUT1: $B < B_{opN}$ , $B_{opS} < B$ ※19 OUT2: $B_{rpN} < B < B_{rpS}$ $I_{OUT} = +0.5mA$
Supply Current 1	$I_{DD1(AVG)}$	-	5	8	$\mu A$	$V_{DD}=1.8V$ , Average
Supply Current During Startup Time 1	$I_{DD1(EN)}$	-	2.8	-	mA	$V_{DD}=1.8V$ , During Startup Time Value
Supply Current During Standby Time 1	$I_{DD1(DIS)}$	-	1.8	-	$\mu A$	$V_{DD}=1.8V$ , During Standby Time Value
Supply Current 2	$I_{DD2(AVG)}$	-	8	12	$\mu A$	$V_{DD}=2.7V$ , Average
Supply Current During Startup Time 2	$I_{DD2(EN)}$	-	4.5	-	mA	$V_{DD}=2.7V$ , During Startup Time Value
Supply Current During Standby Time 2	$I_{DD2(DIS)}$	-	4.0	-	$\mu A$	$V_{DD}=2.7V$ , During Standby Time Value

※19 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.

Radiation hardness is not designed.

BU52001GUL (Unless otherwise specified,  $V_{DD}=3.0V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	2.4	3.0	3.3	V	
Operate Point	$B_{opS}$	-	3.7	5.5	mT	
	$B_{opN}$	-5.5	-3.7	-		
Release Point	$B_{rpS}$	0.8	2.9	-	mT	
	$B_{rpN}$	-	-2.9	-0.8		
Hysteresis	$B_{hysS}$	-	0.8	-	mT	
	$B_{hysN}$	-	0.8	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.4$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -1.0mA$ ※20
Output Low Voltage	$V_{OL}$	-	-	0.4	V	$B < B_{opN}, B_{opS} < B$ $I_{OUT} = +1.0mA$ ※20
Supply Current	$I_{DD(AVG)}$	-	8	12	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	4.7	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	3.8	-	$\mu A$	During Standby Time Value

※20 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.  
 After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.  
 Radiation hardness is not designed.

BU52061NVX (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.60	V	
Operate Point	$B_{opS}$	2.3	3.3	4.7	mT	
	$B_{opN}$	-4.7	-3.3	-2.3		
Release Point	$B_{rpS}$	1.2	2.4	3.4	mT	
	$B_{rpN}$	-3.4	-2.4	-1.2		
Hysteresis	$B_{hysS}$	-	0.9	-	mT	
	$B_{hysN}$	-	0.9	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※21
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※21
Supply Current 1	$I_{DD1(AVG)}$	-	4	7	$\mu A$	$V_{DD}=1.8V$ , Average
Supply Current During Startup Time 1	$I_{DD1(EN)}$	-	5.0	-	mA	$V_{DD}=1.8V$ , During Startup Time Value
Supply Current During Standby Time 1	$I_{DD1(DIS)}$	-	1.8	-	$\mu A$	$V_{DD}=1.8V$ , During Standby Time Value
Supply Current 2	$I_{DD2(AVG)}$	-	9	16	$\mu A$	$V_{DD}=3.0V$ , Average
Supply Current During Startup Time 2	$I_{DD2(EN)}$	-	9.0	-	mA	$V_{DD}=3.0V$ , During Startup Time Value
Supply Current During Standby Time 2	$I_{DD2(DIS)}$	-	4.4	-	$\mu A$	$V_{DD}=3.0V$ , During Standby Time Value

※21 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.

Radiation hardness is not designed.



BU52053NVX (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.60	V	
Operate Point	$B_{opS}$	-	3.0	5.0	mT	
	$B_{opN}$	-5.0	-3.0	-		
Release Point	$B_{rpS}$	0.6	2.1	-	mT	
	$B_{rpN}$	-	-2.1	-0.6		
Hysteresis	$B_{hysS}$	-	0.9	-	mT	
	$B_{hysN}$	-	0.9	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※22
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※22
Supply Current	$I_{DD(AVG)}$	-	5	8	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	2.8	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	1.8	-	$\mu A$	During Standby Time Value

※22 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.  
 After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.  
 Radiation hardness is not designed.

BU52051NVX , BU52011HFV (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.30	V	
Operate Point	$B_{opS}$	-	3.0	5.0	mT	
	$B_{opN}$	-5.0	-3.0	-		
Release Point	$B_{rpS}$	0.6	2.1	-	mT	
	$B_{rpN}$	-	-2.1	-0.6		
Hysteresis	$B_{hysS}$	-	0.9	-	mT	
	$B_{hysN}$	-	0.9	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※23
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※23
Supply Current 1	$I_{DD1(AVG)}$	-	5	8	$\mu A$	$V_{DD}=1.8V$ , Average
Supply Current During Startup Time 1	$I_{DD1(EN)}$	-	2.8	-	mA	$V_{DD}=1.8V$ , During Startup Time Value
Supply Current During Standby Time 1	$I_{DD1(DIS)}$	-	1.8	-	$\mu A$	$V_{DD}=1.8V$ , During Standby Time Value
Supply Current 2	$I_{DD2(AVG)}$	-	8	12	$\mu A$	$V_{DD}=2.7V$ , Average
Supply Current During Startup Time 2	$I_{DD2(EN)}$	-	4.5	-	mA	$V_{DD}=2.7V$ , During Startup Time Value
Supply Current During Standby Time 2	$I_{DD2(DIS)}$	-	4.0	-	$\mu A$	$V_{DD}=2.7V$ , During Standby Time Value

※23 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.

Radiation hardness is not designed.

BU52056NVX (Unless otherwise specified,  $V_{DD}=1.80V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	1.65	1.80	3.60	V	
Operate Point	$B_{opS}$	-	4.6	6.4	mT	
	$B_{opN}$	-6.4	-4.6	-		
Release Point	$B_{rpS}$	2.0	3.8	-	mT	
	$B_{rpN}$	-	-3.8	-2.0		
Hysteresis	$B_{hysS}$	-	0.8	-	mT	
	$B_{hysN}$	-	0.8	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.2$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -0.5mA$ ※24
Output Low Voltage	$V_{OL}$	-	-	0.2	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +0.5mA$ ※24
Supply Current	$I_{DD(AVG)}$	-	5	8	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	2.8	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	1.8	-	$\mu A$	During Standby Time Value

※24 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.  
 After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.  
 Radiation hardness is not designed.

BU52021HFV, BU52025G (Unless otherwise specified,  $V_{DD}=3.0V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	2.4	3.0	3.6	V	
Operate Point	$B_{opS}$	-	3.7	5.5	mT	
	$B_{opN}$	-5.5	-3.7	-		
Release Point	$B_{rpS}$	0.8	2.9	-	mT	
	$B_{rpN}$	-	-2.9	-0.8		
Hysteresis	$B_{hysS}$	-	0.8	-	mT	
	$B_{hysN}$	-	0.8	-		
Period	$T_p$	-	50	100	ms	
Output High Voltage	$V_{OH}$	$V_{DD}-0.4$	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -1.0mA$ ※25
Output Low Voltage	$V_{OL}$	-	-	0.4	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +1.0mA$ ※25
Supply Current	$I_{DD(AVG)}$	-	8	12	$\mu A$	Average
Supply Current During Startup Time	$I_{DD(EN)}$	-	4.7	-	mA	During Startup Time Value
Supply Current During Standby Time	$I_{DD(DIS)}$	-	3.8	-	$\mu A$	During Standby Time Value

※25 B = Magnetic flux density  
 1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period ( $T_p$ ) to become definite output.

Radiation hardness is not designed.

BD7411G (Unless otherwise specified,  $V_{DD}=5.0V$ ,  $T_a=25^{\circ}C$ )

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Power Supply Voltage	$V_{DD}$	4.5	5.0	5.5	V	
Operate Point	$B_{opS}$	-	3.4	5.6	mT	
	$B_{opN}$	-5.6	-3.4	-		
Release Point	$B_{rpS}$	1.5	3.0	-	mT	
	$B_{rpN}$	-	-3.0	-1.5		
Hysteresis	$B_{hysS}$	-	0.4	-	mT	
	$B_{hysN}$	-	0.4	-		
Output High Voltage	$V_{OH}$	4.6	-	-	V	$B_{rpN} < B < B_{rpS}$ $I_{OUT} = -1.0mA$ ※26
Output Low Voltage	$V_{OL}$	-	-	0.4	V	$B < B_{opN}$ , $B_{opS} < B$ $I_{OUT} = +1.0mA$ ※26
Supply Current	$I_{DD}$	-	2	4	mA	

※26 B = Magnetic flux density

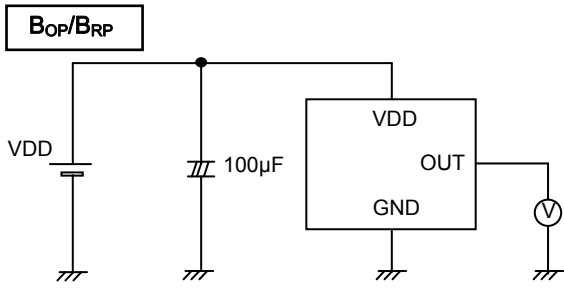
1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

Radiation hardness is not designed.

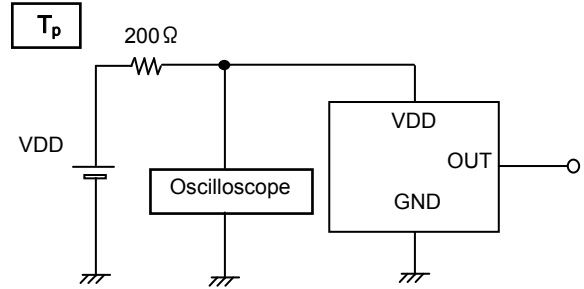


● Figure of measurement circuit



Bop and Brp are measured with applying the magnetic field from the outside.

Fig.1 B<sub>op</sub>, B<sub>rp</sub> measurement circuit



The period is monitored by Oscilloscope.

Fig.2 T<sub>p</sub> measurement circuit

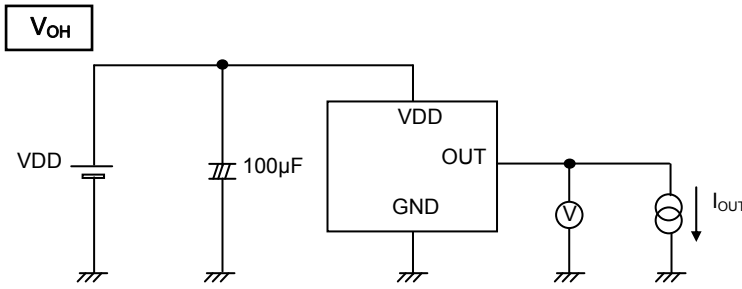


Fig.3 V<sub>OH</sub> measurement circuit

Product Name	I <sub>OUT</sub>
BU52001GUL, BU52021HFV, BU52025G, BD7411G	1.0mA
BU52054GWZ, BU52055GWZ, BU52015GUL, BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX, BU52011HFV	0.5mA

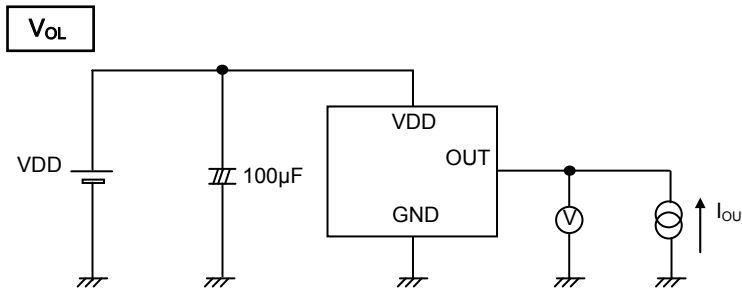


Fig.4 V<sub>OL</sub> measurement circuit

Product Name	I <sub>OUT</sub>
BU52001GUL, BU52021HFV, BU52025G, BD7411G	1.0mA
BU52054GWZ, BU52055GWZ, BU52015GUL, BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX, BU52011HFV	0.5mA

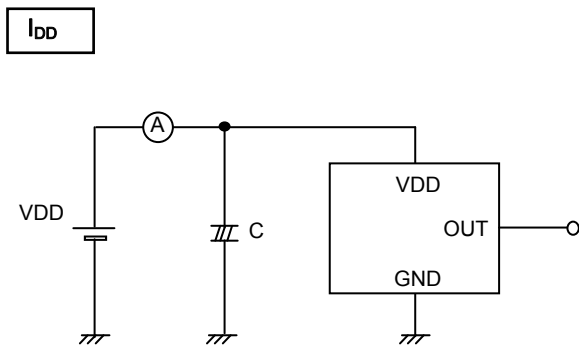


Fig.5 I<sub>DD</sub> measurement circuit

Product Name	C
BU52054GWZ, BU52055GWZ, BU52015GUL, BU52001GUL, BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX, BU52011HFV, BU52021HFV, BU52025G	2200µF
BD7411G	100µF

● Technical (Reference) Data

**BU52054GWZ (V<sub>DD</sub>=1.65~3.6V type)**

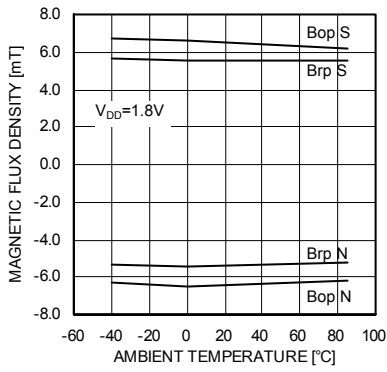


Fig. 6 Bop, Brp - Ambient temperature

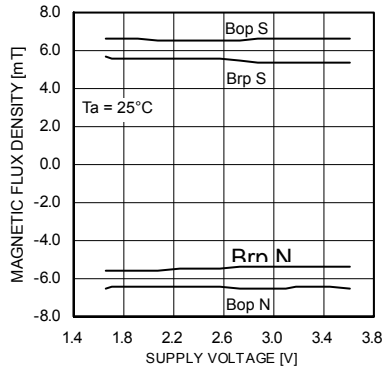


Fig. 7 Bop, Brp - Supply voltage

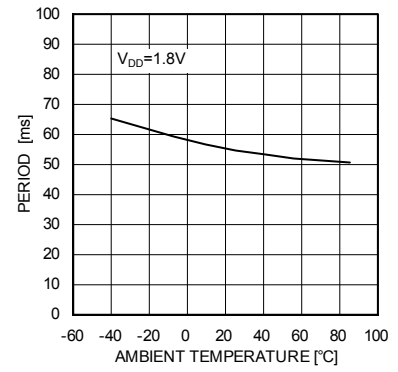


Fig. 8 T<sub>P</sub> - Ambient temperature

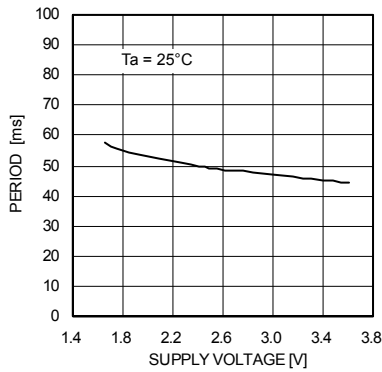


Fig. 9 T<sub>P</sub> - Supply voltage

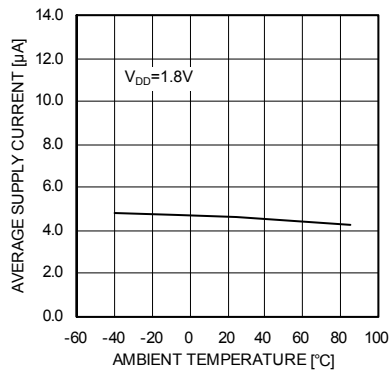


Fig. 10 I<sub>DD</sub> - Ambient temperature

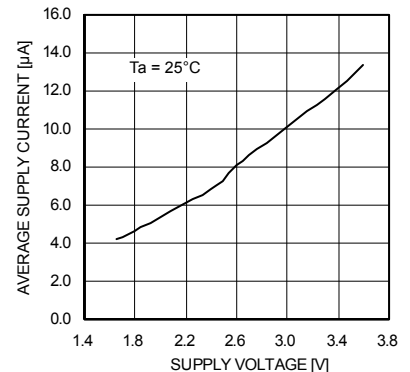


Fig. 11 I<sub>DD</sub> - Supply voltage

**BU52055GWZ (V<sub>DD</sub>=1.65~3.6V type)**

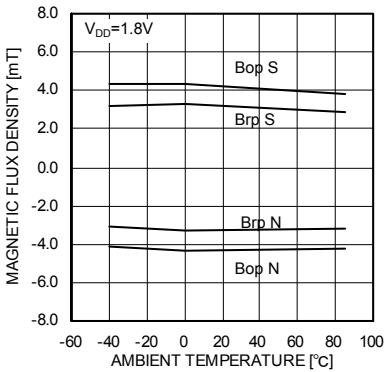


Fig. 12 Bop, Brp - Ambient temperature

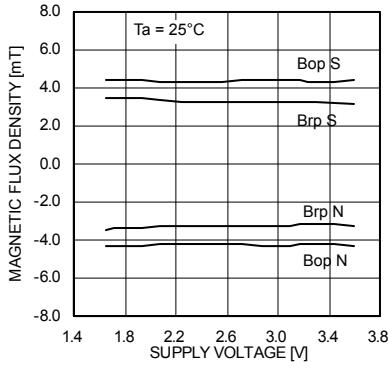


Fig. 13 Bop, Brp - Supply voltage

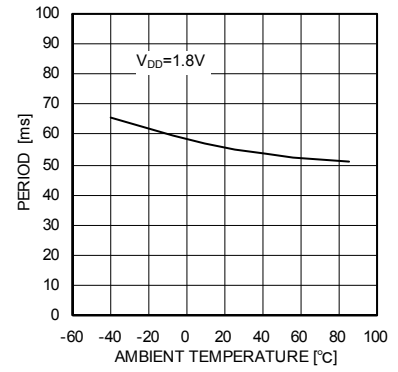


Fig. 14 T<sub>P</sub> - Ambient temperature

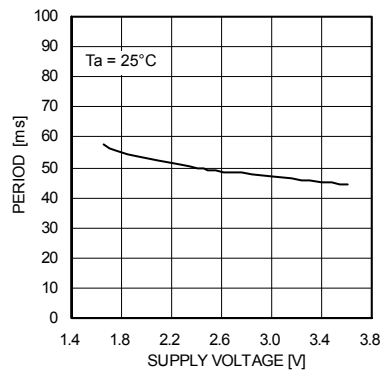


Fig. 15 T<sub>P</sub> - Supply voltage

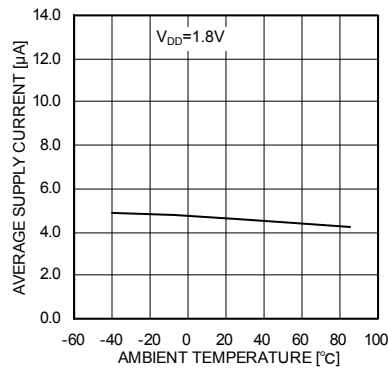


Fig. 16 I<sub>DD</sub> - Ambient temperature

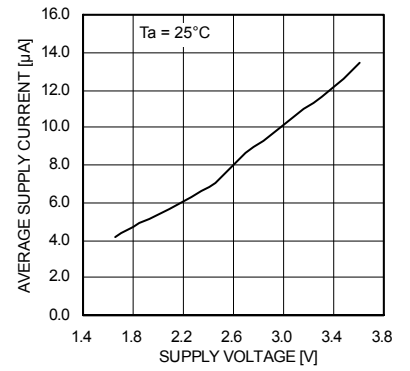


Fig. 17 I<sub>DD</sub> - Supply voltage

**BU52015GUL, BU52051NVX, BU52011HFV ( $V_{DD}=1.65\sim 3.3V$  type)**

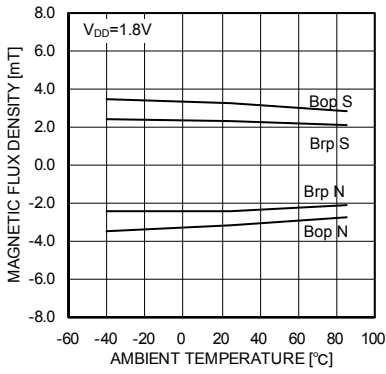


Fig.18 Bop,Brp- Ambient temperature

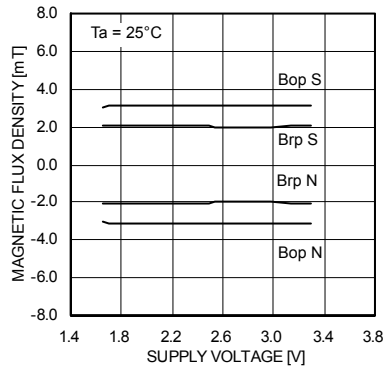


Fig.19 Bop,Brp Supply voltage

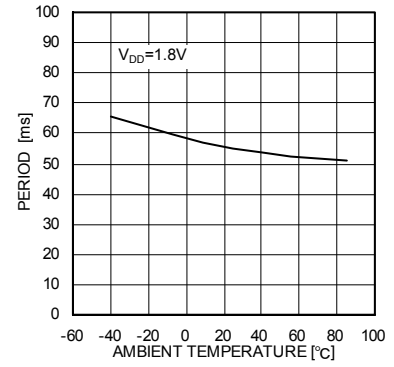


Fig.20  $T_P$  - Ambient temperature

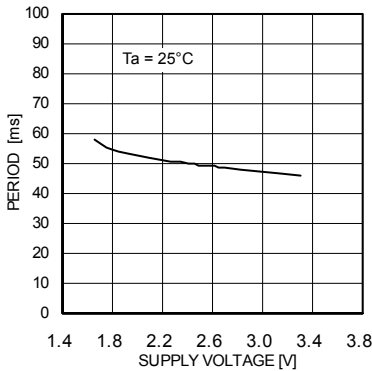


Fig.21  $T_P$ - Supply voltage

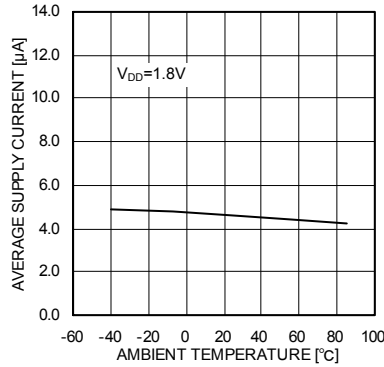


Fig.22  $I_{DD}$ - Ambient temperature

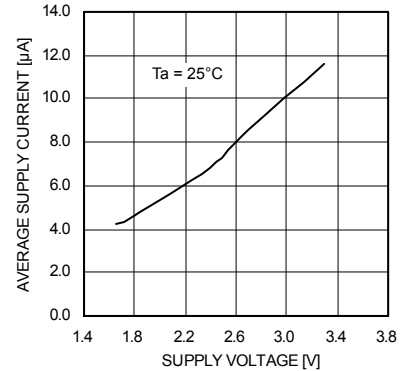


Fig.23  $I_{DD}$  - Supply voltage

**BU52001GUL ( $V_{DD}=2.4\sim 3.3V$  type)**

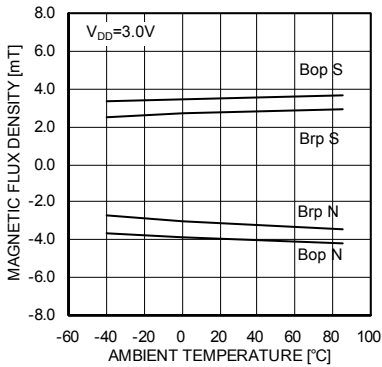


Fig.24 Bop,Brp- Ambient temperature

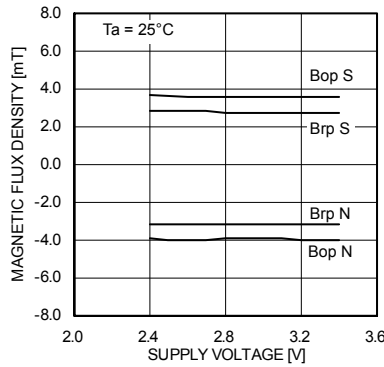


Fig.25 Bop,Brp- Supply voltage

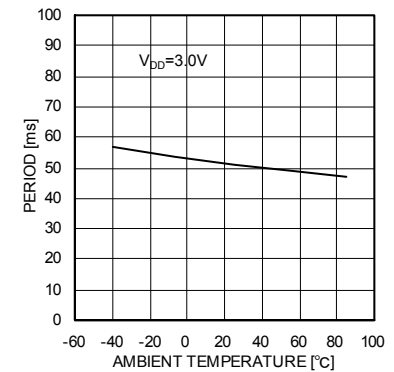


Fig.26  $T_P$ - Ambient temperature

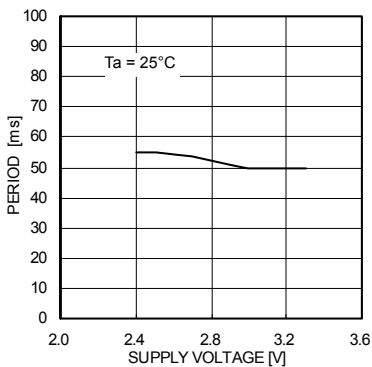


Fig.27  $T_P$ - Supply voltage

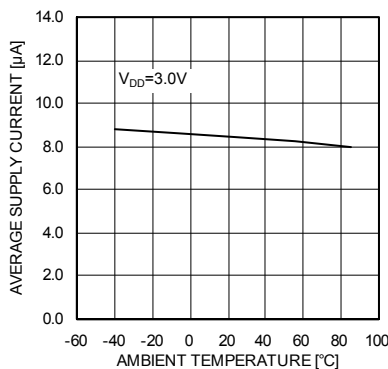


Fig.28  $I_{DD}$ - Ambient temperature

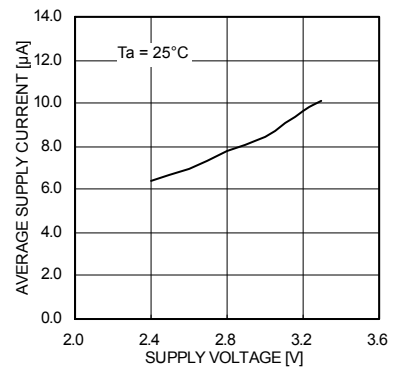


Fig.29  $I_{DD}$  - Supply voltage

**BU52061NVX (V<sub>DD</sub>=1.65~3.6V type)**

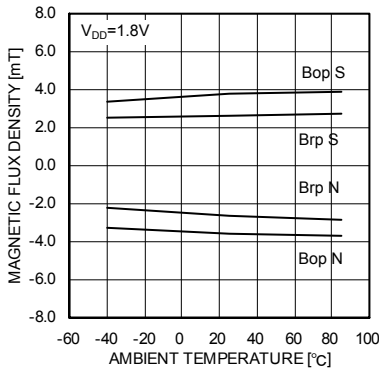


Fig.30 Bop, Brp– Ambient temperature

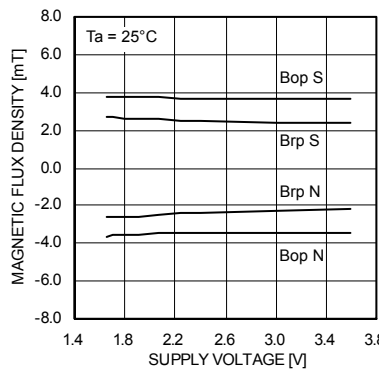


Fig.31 Bop, Brp– Supply voltage

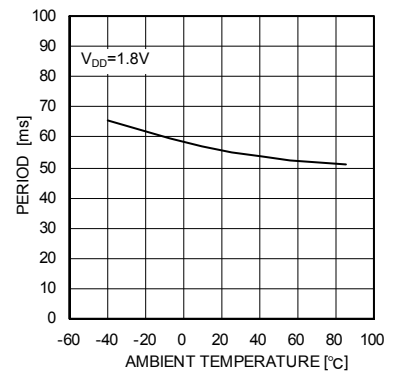


Fig.32 T<sub>P</sub> – Ambient temperature

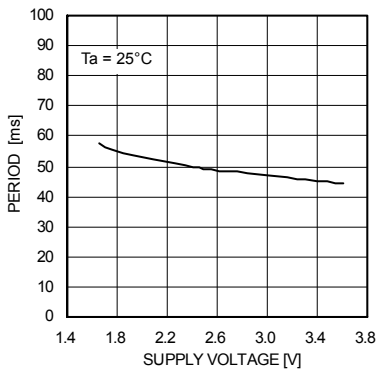


Fig.33 T<sub>P</sub>– Supply voltage

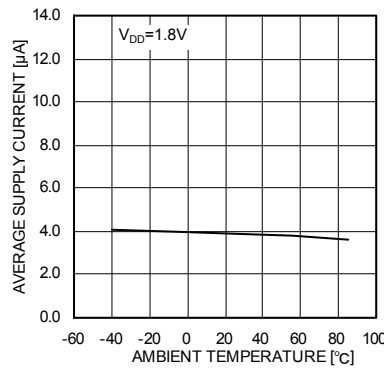


Fig.34 I<sub>DD</sub>– Ambient temperature

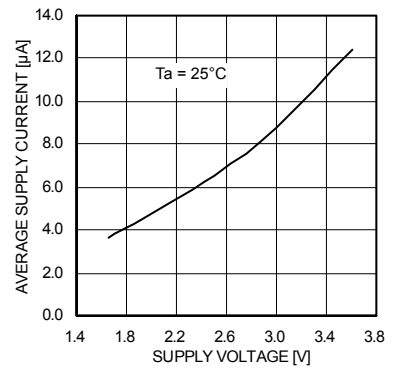


Fig.35 I<sub>DD</sub> – Supply voltage

**BU52053NVX (V<sub>DD</sub>=1.65~3.6V type)**

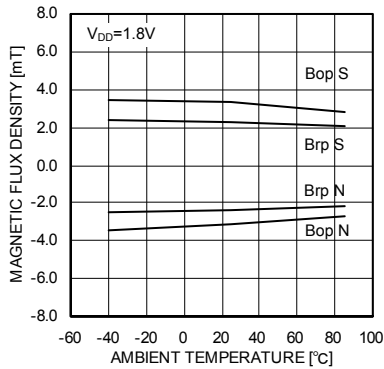


Fig.36 Bop, Brp– Ambient temperature

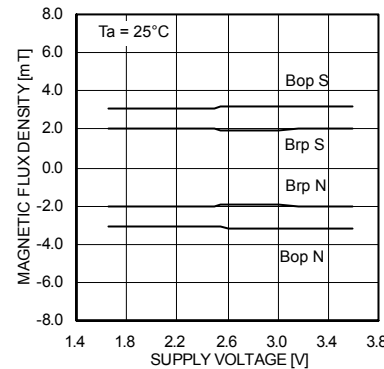


Fig.37 Bop, Brp– Supply voltage

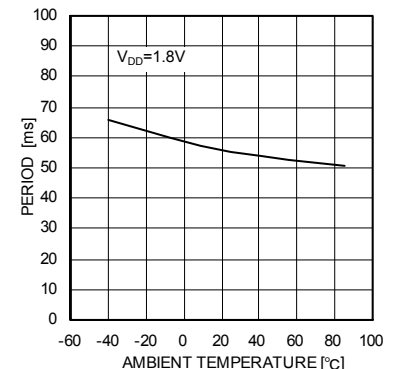


Fig.38 T<sub>P</sub> – Ambient temperature

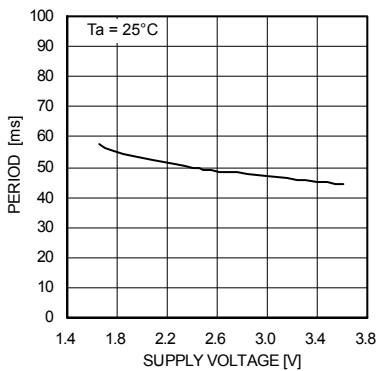


Fig.39 T<sub>P</sub>– Supply voltage

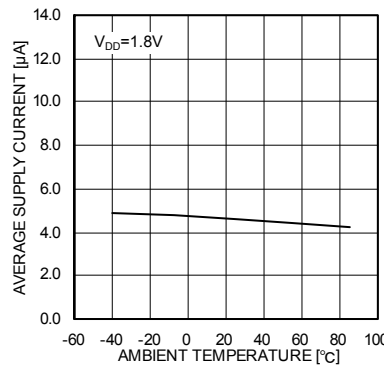


Fig.40 I<sub>DD</sub>– Ambient temperature

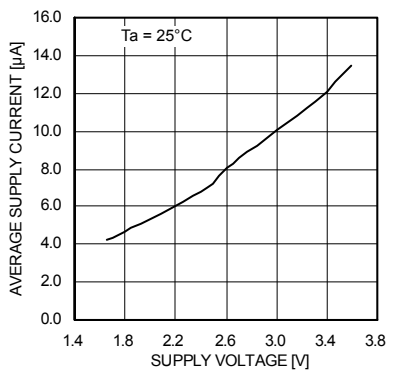


Fig.41 I<sub>DD</sub> – Supply voltage

**BU52056NVX (V<sub>DD</sub>=1.65~3.6V type)**

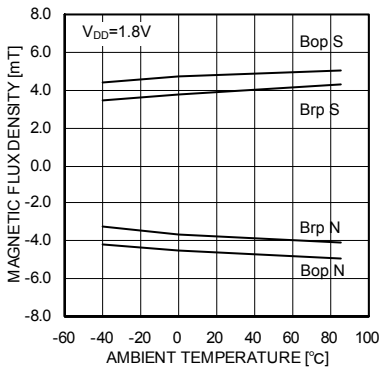


Fig.42 Bop,Brp– Ambient temperature

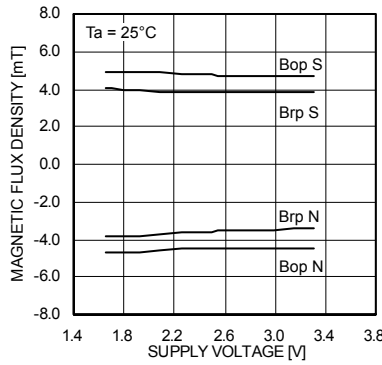


Fig.43 Bop,Brp– Supply voltage

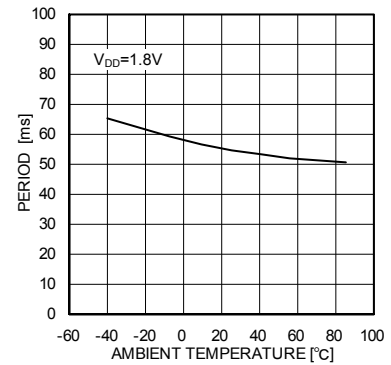


Fig.44 T<sub>P</sub> – Ambient temperature

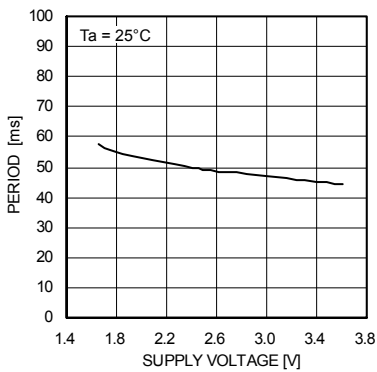


Fig.45 T<sub>P</sub>– Supply voltage

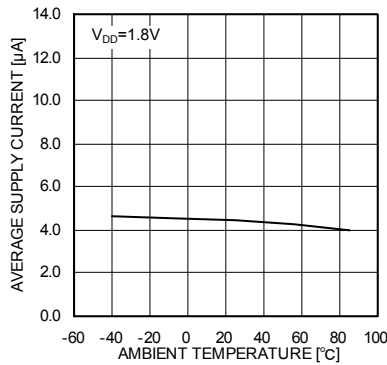


Fig.46 I<sub>DD</sub>– Ambient temperature

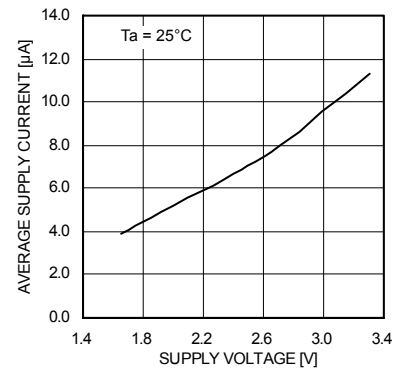


Fig.47 I<sub>DD</sub>– Supply voltage

**BU52021HFV, BU52025G (V<sub>DD</sub>=2.4~3.6V type)**

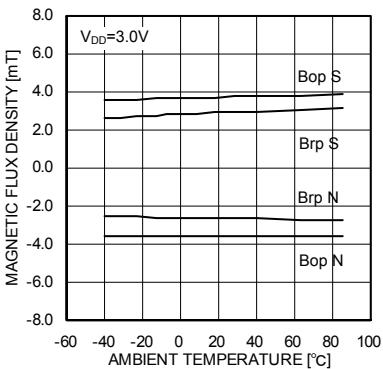


Fig.48 Bop,Brp–Ambient temperature

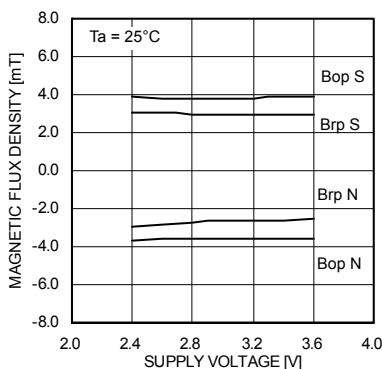


Fig.49 Bop,Brp– Supply voltage

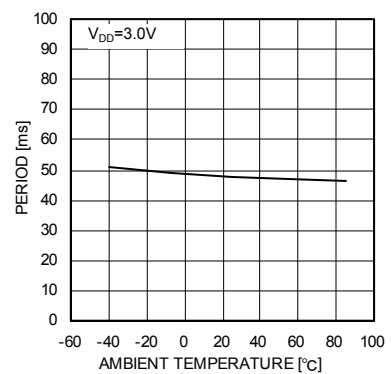


Fig.50 T<sub>P</sub> – Ambient temperature

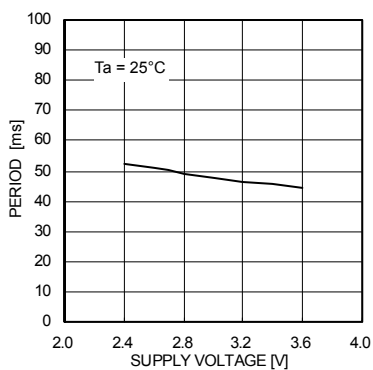


Fig.51 T<sub>P</sub> – Supply voltage

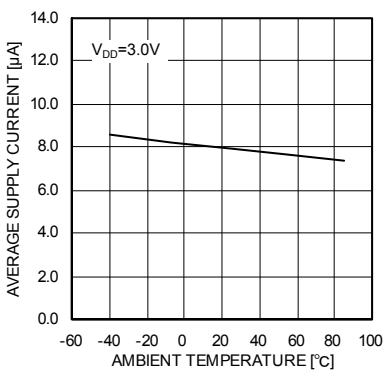


Fig.52 I<sub>DD</sub> – Ambient temperature

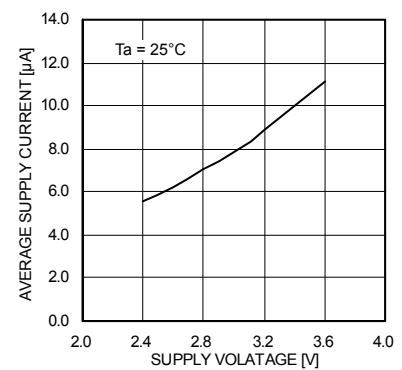


Fig.53 I<sub>DD</sub> – Supply voltage



**BD7411G (V<sub>DD</sub>=4.5~5.5V type)**

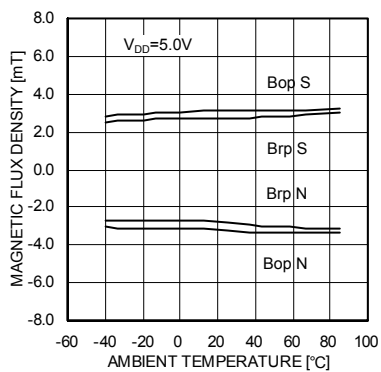


Fig.54 Bop,Brp–Ambient temperature

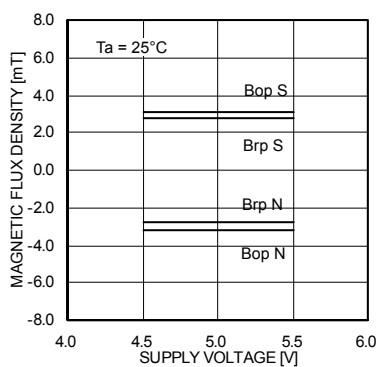


Fig.55 Bop,Brp– Supply voltage

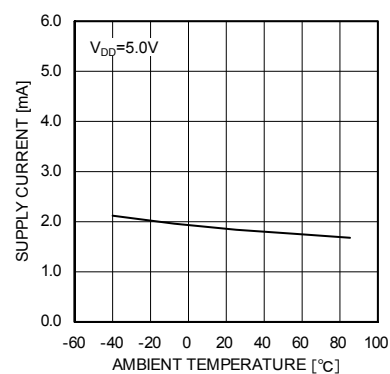


Fig.56 I<sub>DD</sub> – Ambient temperature

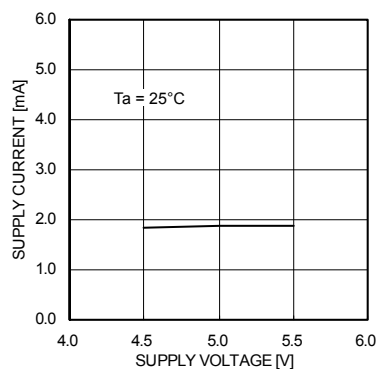
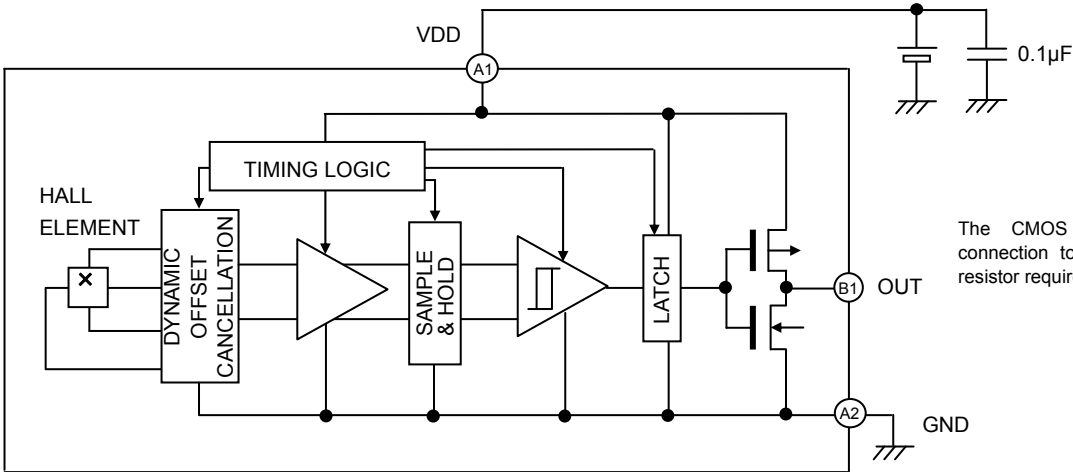


Fig.57 I<sub>DD</sub> – Supply voltage

● Block Diagram  
**BU52054GWZ, BU52055GWZ**

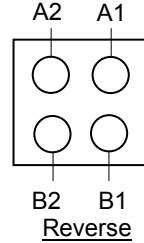
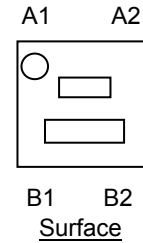


Adjust the bypass capacitor value as necessary, according to voltage noise conditions, etc.

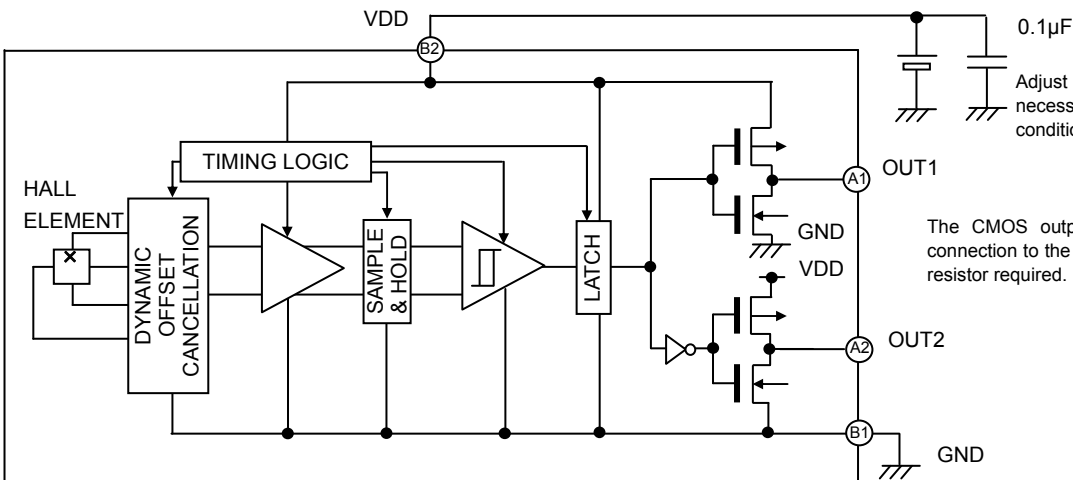
The CMOS output terminals enable direct connection to the PC, with no external pull-up resistor required.

Fig.58

PIN No.	PIN NAME	FUNCTION	COMMENT
A1	GND	GROUND	
A2	GND	GROUND	
B1	VDD	POWER SUPPLY	
B2	OUT	OUTPUT	



**BU52015GUL**

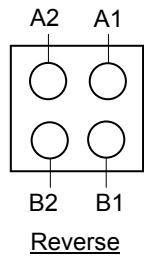
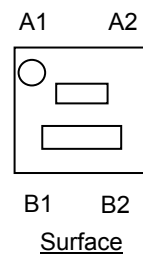


Adjust the bypass capacitor value as necessary, according to voltage noise conditions, etc.

The CMOS output terminals enable direct connection to the PC, with no external pull-up resistor required.

Fig.59

PIN No.	PIN NAME	FUNCTION	COMMENT
A1	OUT1	Output pin (Active Low)	
A2	OUT2	Output pin (Active High)	
B1	GND	GROUND	
B2	VDD	Power Supply Voltage	



**BU52001GUL**

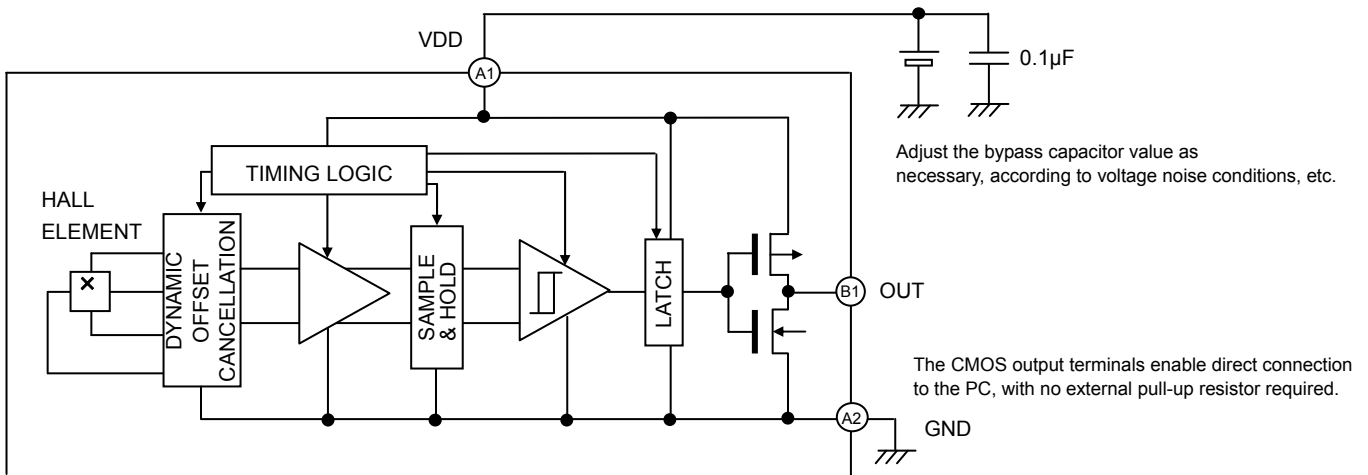
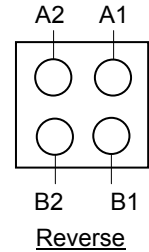
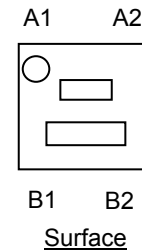


Fig.60

PIN No.	PIN NAME	FUNCTION	COMMENT
A1	VDD	POWER SUPPLY	
A2	GND	GROUND	
B1	OUT	OUTPUT	
B2	N.C.		OPEN or Short to GND.



**BU52061NVX, BU52053NVX, BU52051NVX, BU52056NVX**

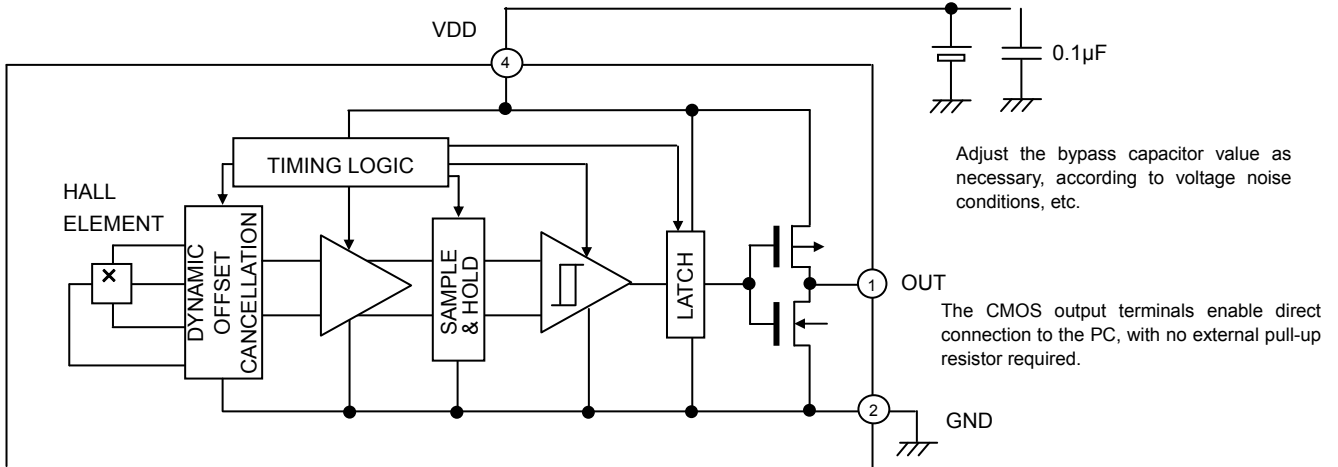
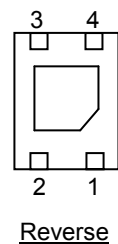
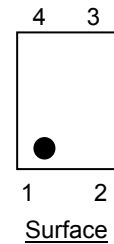


Fig.61

PIN No.	PIN NAME	FUNCTION	COMMENT
1	OUT	OUTPUT	
2	GND	GROUND	
3	N.C.		OPEN or Short to GND.
4	VDD	POWER SUPPLY	



**BU52011HFV, BU52021HFV**

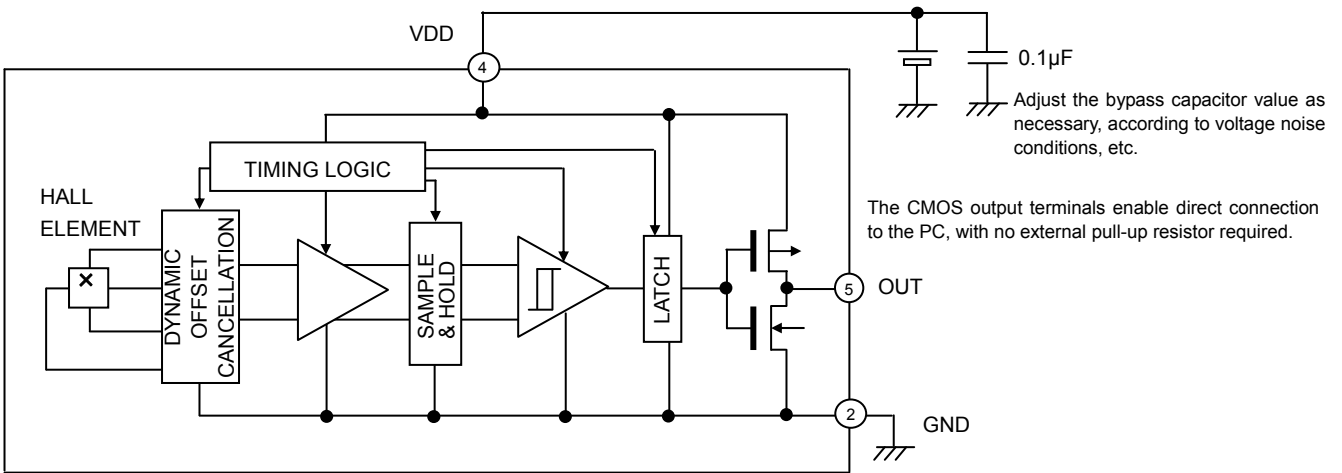
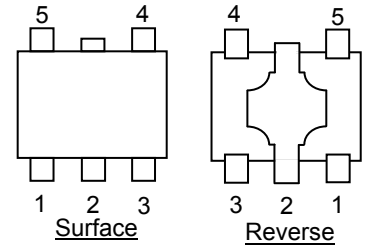


Fig.62

PIN No.	PIN NAME	FUNCTION	COMMENT
1	N.C.		OPEN or Short to GND.
2	GND	GROUND	
3	N.C.		OPEN or Short to GND.
4	VDD	POWER SUPPLY	
5	OUT	OUTPUT	



**BU52025G**

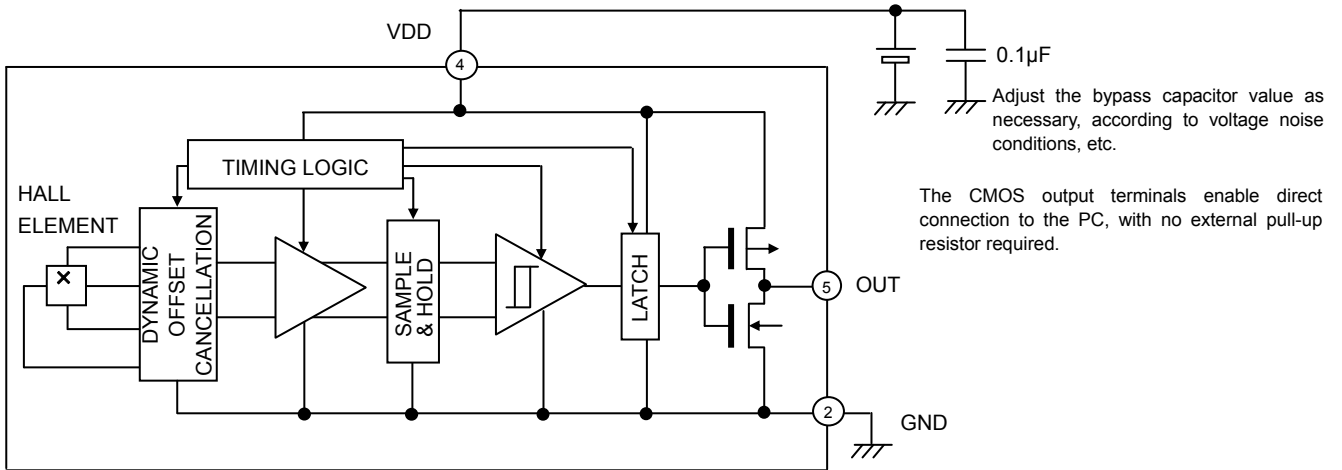
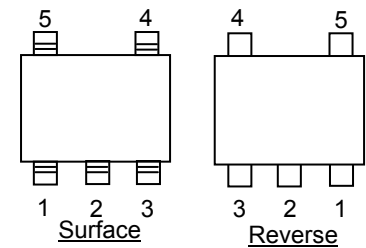


Fig.63

PIN No.	PIN NAME	FUNCTION	COMMENT
1	N.C.		OPEN or Short to GND.
2	GND	GROUND	
3	N.C.		OPEN or Short to GND.
4	VDD	POWER SUPPLY	
5	OUT	OUTPUT	



**BD7411G**

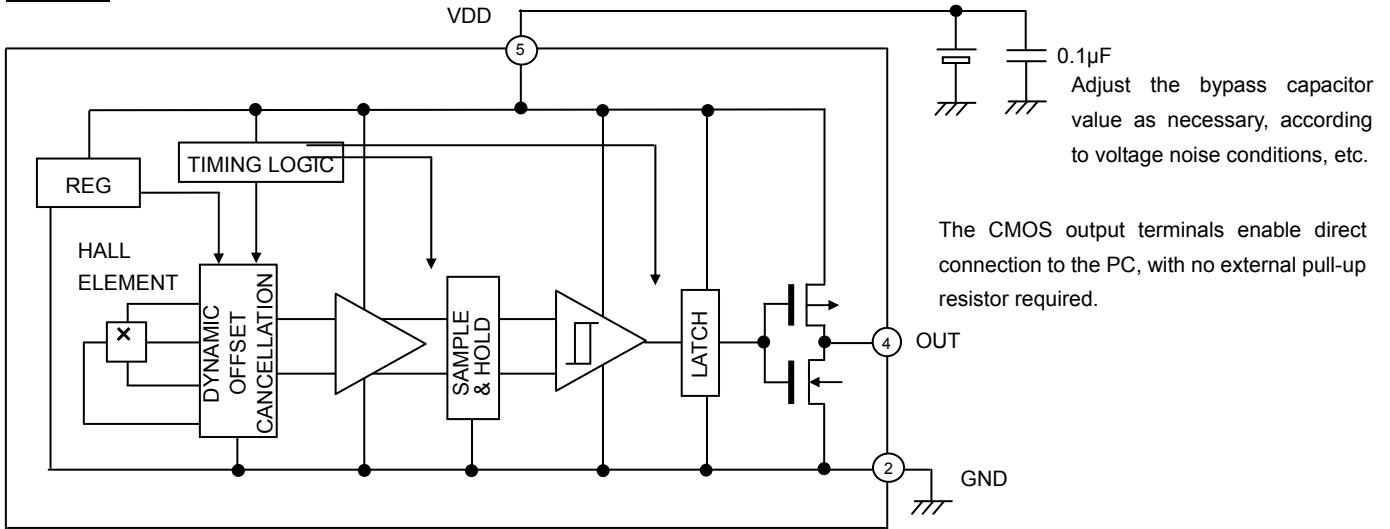
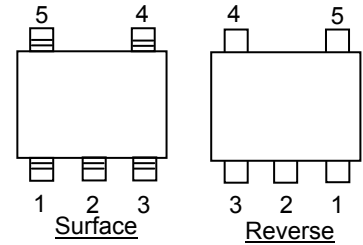


Fig.64

PIN No.	PIN NAME	FUNCTION	COMMENT
1	N.C.		OPEN or Short to GND.
2	GND	GROUND	
3	N.C.		OPEN or Short to GND.
4	OUT	OUTPUT	
5	VDD	POWER SUPPLY	





●Description of Operations

(Micropower Operation)

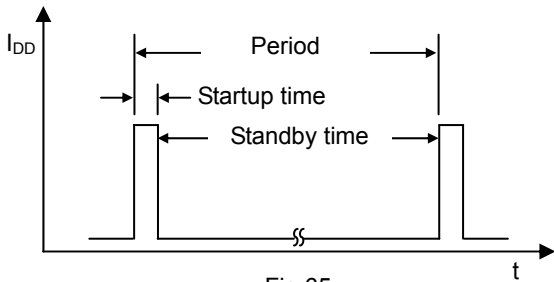


Fig.65

The bipolar detection Hall IC adopts an intermittent operation method to save energy. At startup, the Hall elements, amp, comparator and other detection circuits power ON and magnetic detection begins. During standby, the detection circuits power OFF, thereby reducing current consumption. The detection results are held while standby is active, and then output.

Reference period: 50ms (MAX100ms)  
 Reference startup time: 48 $\mu$ s

※BD7411G don't adopts an intermittent operation method.

(Offset Cancellation)

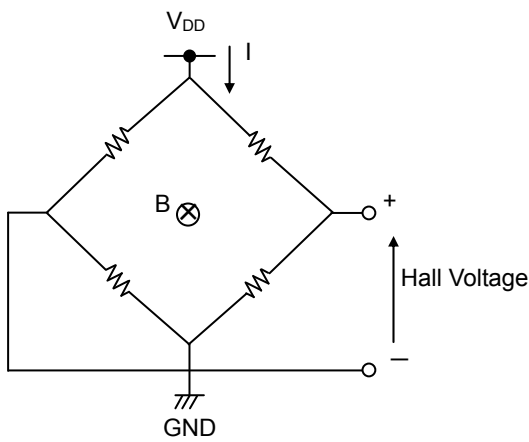


Fig.66

The Hall elements form an equivalent Wheatstone (resistor) bridge circuit. Offset voltage may be generated by a differential in this bridge resistance, or can arise from changes in resistance due to package or bonding stress. A dynamic offset cancellation circuit is employed to cancel this offset voltage.

When Hall elements are connected as shown in Fig. 66 and a magnetic field is applied perpendicular to the Hall elements, voltage is generated at the mid-point terminal of the bridge. This is known as Hall voltage.

Dynamic cancellation switches the wiring (shown in the figure) to redirect the current flow to a 90° angle from its original path, and thereby cancels the Hall voltage.

The magnetic signal (only) is maintained in the sample/hold circuit during the offset cancellation process and then released.

(Magnetic Field Detection Mechanism)

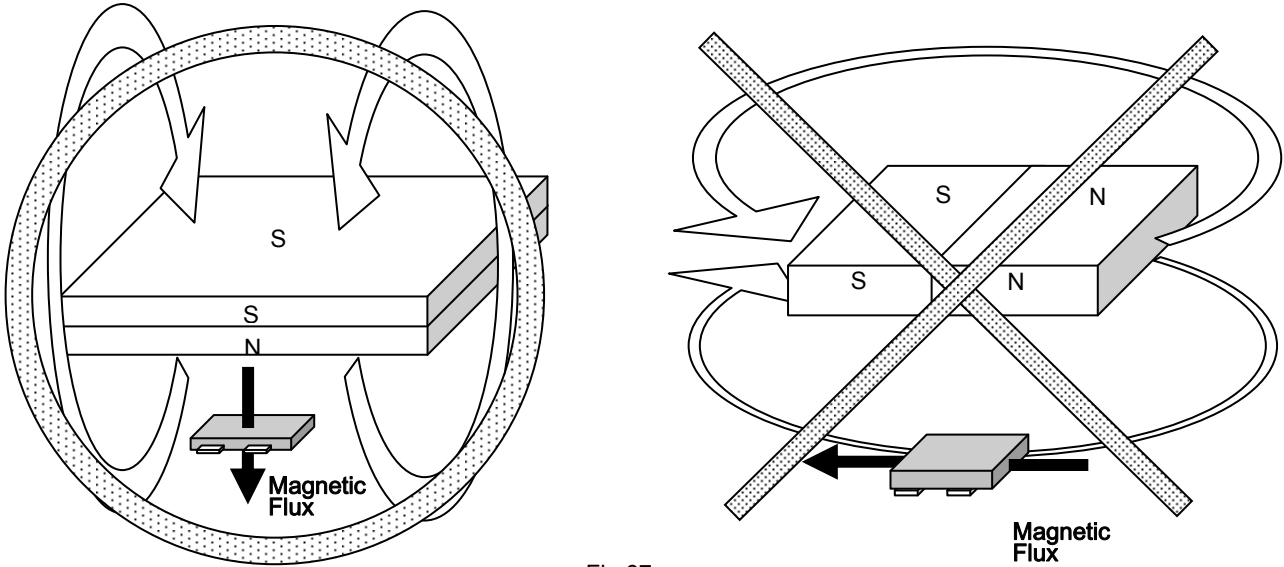


Fig.67

The Hall IC cannot detect magnetic fields that run horizontal to the package top layer. Be certain to configure the Hall IC so that the magnetic field is perpendicular to the top layer.

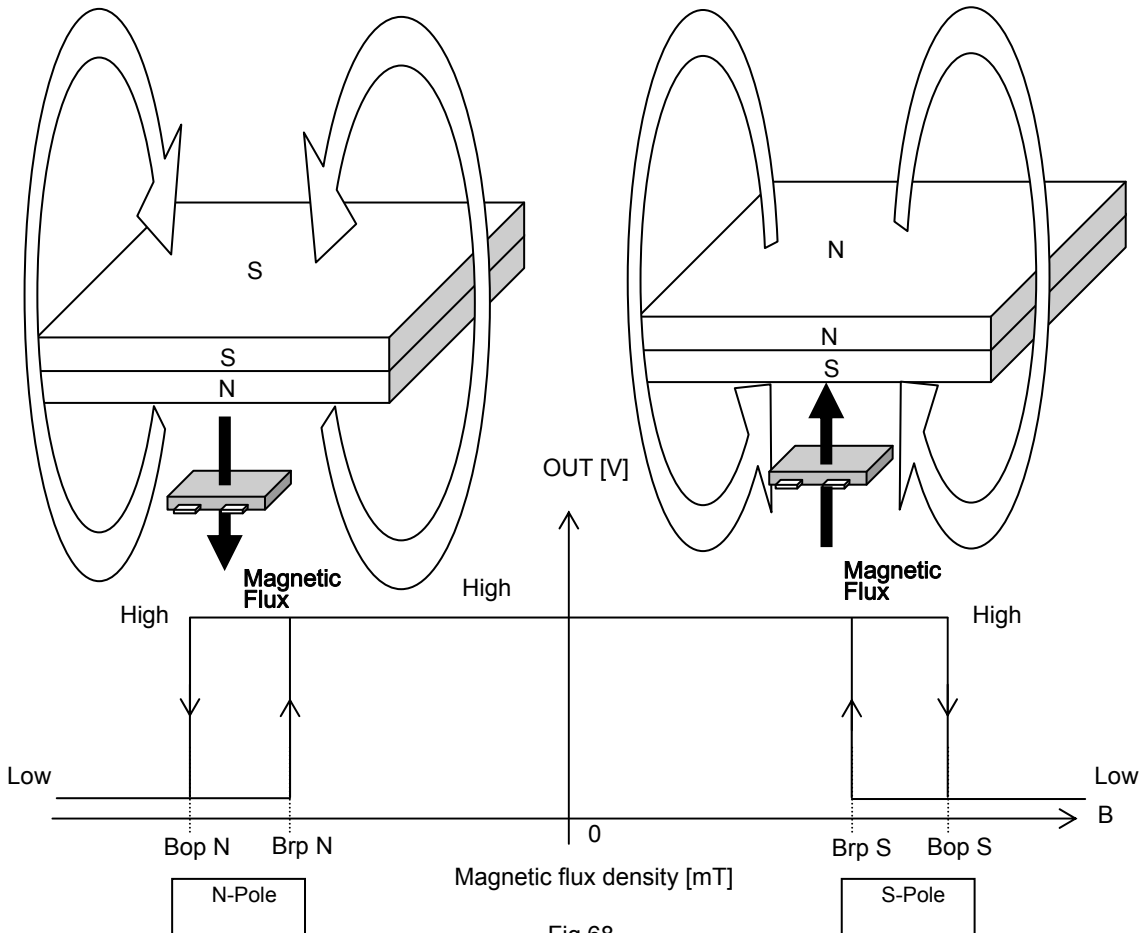


Fig.68

The bipolar detection Hall IC detects magnetic fields running perpendicular to the top surface of the package. There is an inverse relationship between magnetic flux density and the distance separating the magnet and the Hall IC: when distance increases magnetic density falls. When it drops below the operate point (Bop), output goes HIGH. When the magnet gets closer to the IC and magnetic density rises, to the operate point, the output switches LOW. In LOW output mode, the distance from the magnet to the IC increases again until the magnetic density falls to a point just below Bop, and output returns HIGH. (This point, where magnetic flux density restores HIGH output, is known as the release point, Brp.) This detection and adjustment mechanism is designed to prevent noise, oscillation and other erratic system operation.

● Intermittent Operation at Power ON

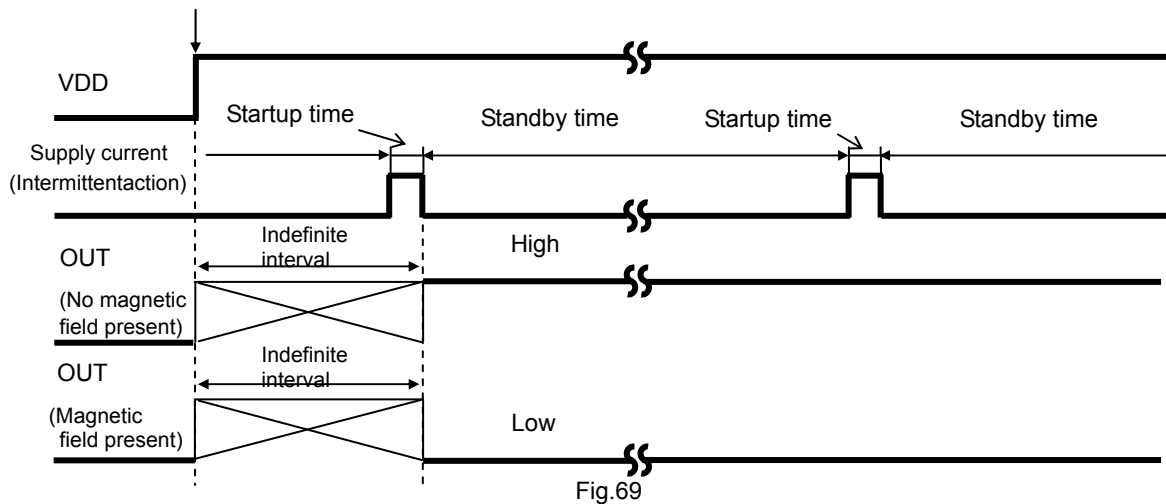


Fig.69

The bipolar detection Hall IC adopts an intermittent operation method in detecting the magnetic field during startup, as shown in Fig. 69. It outputs to the appropriate terminal based on the detection result and maintains the output condition during the standby period. The time from power ON until the end of the initial startup period is an indefinite interval, but it cannot exceed the maximum period, 100ms. To accommodate the system design, the Hall IC output read should be programmed within 100ms of power ON, but after the time allowed for the period ambient temperature and supply voltage. ※BD7411G don't adopts an intermittent operation method.

● Magnet Selection

Of the two representative varieties of permanent magnet, neodymium generally offers greater magnetic power per volume than ferrite, thereby enabling the highest degree of miniaturization. Thus, neodymium is best suited for small equipment applications. Fig. 70 shows the relation between the size (volume) of a neodymium magnet and magnetic flux density. The graph plots the correlation between the distance (L) from three versions of a 4mm X 4mm cross-section neodymium magnet (1mm, 2mm, and 3mm thick) and magnetic flux density. Fig. 71 shows Hall IC detection distance – a good guide for determining the proper size and detection distance of the magnet. Based on the BU52011HFV, BU52015GUL operating point max 5.0 mT, the minimum detection distance for the 1mm, 2mm and 3mm magnets would be 7.6mm, 9.22mm, and 10.4mm, respectively. To increase the magnet's detection distance, either increase its thickness or sectional area.

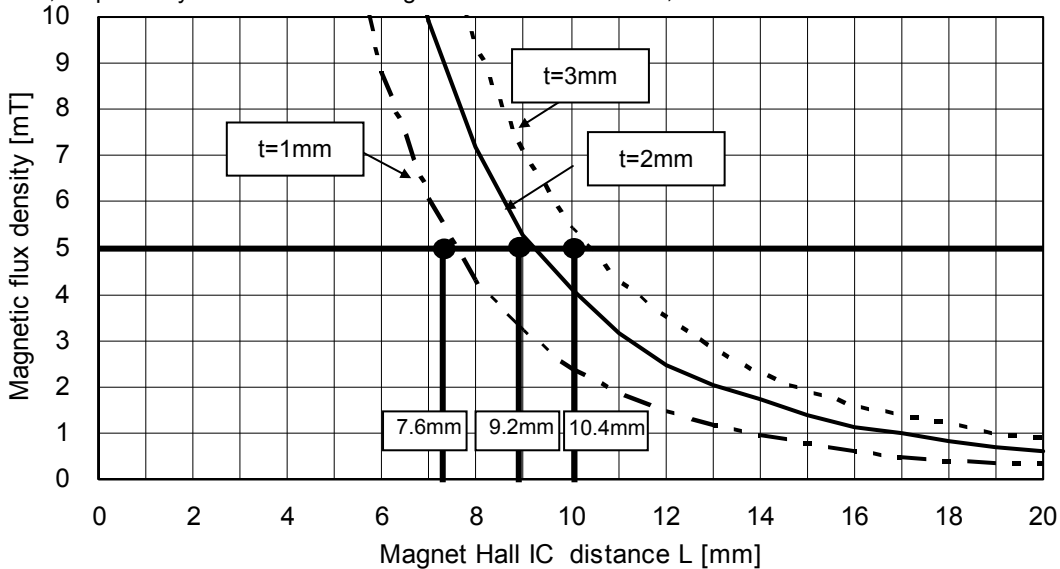
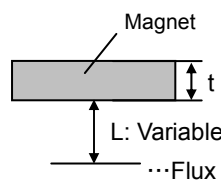
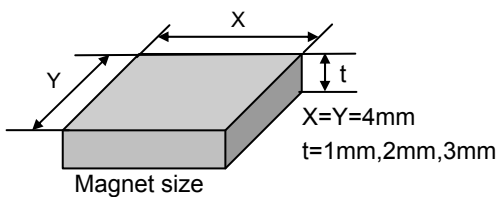


Fig.70



Magnet material: NMX-44CH  
Maker: Hitachi Metals.,LTD

... Flux density measuring point

Fig.71 Magnet Dimensions and Flux Density Measuring Point